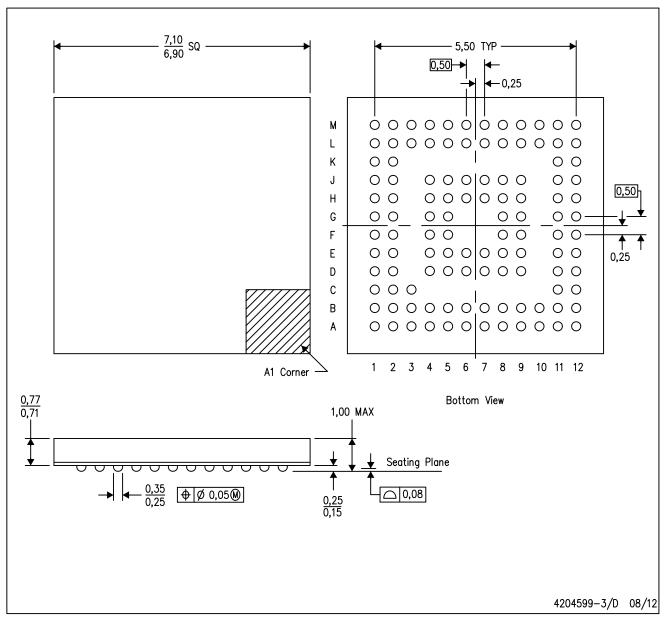
ZQW (S-PBGA-N113)

PLASTIC BALL GRID ARRAY



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MO-225
- D. This is a Pb-free solder ball design.

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